



*The Institute for
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Design Guidelines for Reliable Surface Mount Technology Printed Board Assemblies

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2215 Sanders Road
Northbrook, Illinois
60062-6135

Tel 847 509.9700
Fax 847 509.9798
URL: <http://www.ipc.org>

Table of Contents

1.0 SCOPE	1	3.3 Printed Board Design and Layout.....	10
1.1 Purpose.....	1	3.3.1 Thermal Design and Layout.....	11
1.2 Design Philosophy.....	1	3.3.2 Thermal Design and Conformal Coating.....	11
1.2.1 Establishing the Design Team.....	1	3.3.3 Land Patterns.....	11
1.2.2 Defining Reliability Requirements.....	1	3.3.4 Balance About Neutral Axis.....	11
1.2.3 Understanding the Product Life Cycle.....	1	3.3.5 Vias.....	11
1.2.4 Defining the Product Environment.....	2	3.3.6 Printed Board Trace Widths and Spaces.....	11
1.3 Document Organization.....	2	3.3.7 PTH and PTV Thermal Isolation/Relief.....	12
1.3.1 Applicable Documents.....	2	3.3.8 Test Pads.....	12
1.3.2 Design for Reliability of SM Assemblies.....	2	3.3.9 Spacing Between Parts.....	12
1.3.3 Substrates.....	2	3.3.10 “Pads-Only” Design.....	12
1.3.4 Components.....	2	3.3.11 Components with Reduced Clearances (Traces Under).....	13
1.3.5 Attachment Materials and Coatings.....	2	3.3.12 Components with Reduced Clearance and Open Vias.....	13
1.3.6 Assembly Processes and DfM.....	2	3.4 Coefficient of Thermal Expansion (CTE) and CTE-Mismatch.....	13
1.3.7 Testing.....	3	3.5 Solder Joint Reliability.....	14
1.4 Terms and Definitions.....	3	3.5.1 Primary Design Parameters.....	14
2.0 APPLICABLE DOCUMENTS	5	3.5.2 Secondary Design Parameters.....	15
2.1 Institute for Interconnecting and Packaging Electronic Circuits (IPC).....	5	3.6 Plated-Through Hole and Via Reliability.....	16
2.2 Electronic Industries Association.....	5	3.7 DfR of SM Solder Attachments.....	16
2.3 Joint Industry Standards.....	5	3.8 DfR of Insulation Resistance.....	16
3.0 DESIGN FOR RELIABILITY FOR SURFACE MOUNT ASSEMBLIES	5	4.0 SUBSTRATES	16
3.1 Life Cycle Environment.....	5	4.1 General Substrate Categories.....	16
3.1.1 Manufacturing Processes.....	5	4.2 Substrates and Their Functions:.....	16
3.1.2 Processing Temperature Excursions.....	5	4.3 Moisture and its Effects on Polymer Substrates.....	17
3.1.3 Burn-In and Environmental Stress Screening (ESS).....	6	4.4 Coefficient of Thermal Expansion (CTE) of Polymer Systems.....	17
3.1.4 Transport.....	6	4.5 Constraining Cores in Substrates.....	17
3.1.5 Storage.....	6	4.5.1 Printed Board Stiffness and Damping.....	19
3.1.6 Use Environments.....	6	4.6 Flexible Printed Board with Metal Support Plane.....	19
3.1.7 Environmental Stresses.....	7	4.7 Discrete Wire Structures with Metal Support Plane.....	19
3.1.8 Temperature/Thermal.....	7	4.8 Outgassing of Polymer Substrates.....	19
3.1.9 Cyclic Temperature Swings.....	7	4.9 Assembly Process Effects on Polymer Substrates.....	19
3.1.10 Thermal Shock.....	7	4.10 Printed Board Solderability.....	19
3.1.11 Electrical.....	8	4.11 Design for Reliability of Plated-Through-Hole Vias (PTVs).....	19
3.1.12 EMC/EMI.....	8	5.0 GENERAL COMPONENT SELECTION CONSIDERATIONS	19
3.1.13 Mechanical Shock and Vibration.....	8	5.1 Component Selection Strategy.....	20
3.1.14 Insulation Resistance.....	9	5.2 Package Leadframe and Local Materials.....	20
3.1.15 Solvent Compatibility.....	10		
3.1.16 Corrosion.....	10		
3.1.17 External Radiation.....	10		
3.1.18 Space Environment.....	10		
3.2 Thermal Design.....	10		

5.3	Package Lead Configuration Selection	20	8.2	Testing Philosophy.....	29
5.3.1	Gull Wing Components	20	9.0 REFERENCE DOCUMENTS		29
5.3.2	J-Lead Components	20	9.1	General Books on SMT Process and Design ..	29
5.3.3	Pin Grid Arrays.....	20	9.2	SMT Soldering Process Technical Details.....	30
5.3.4	Fine Pitch Components.....	20	9.3	SMT Solder Paste	30
5.3.5	Plastic Surface Mount Components (PSMC)	21	9.4	SMT Cleaning.....	30
5.3.6	Component Termination Coplanarity and Configuration.....	21	9.5	Solder Joint Reliability	30
5.3.7	Component Lead Configuration	21	9.6	Design of Electronic Packages and Packaging	30
5.4	Component Termination Finishes.....	21	9.7	EMC, High Speed Transients and Electrical Overstress.....	31
5.4.1	Nickel Barrier Layer.....	21	9.8	ESD	31
5.4.2	Tin and Tin-Lead Solder Termination Finishes	21	9.9	Scanning Acoustic Microscopy	31
5.4.3	Termination Recommendations When Using Electrically Conductive Adhesives.....	22	9.10	Plastic Package Cracking	31
5.4.4	Gold, Palladium, Silver Termination Finishes..	22	9.11	Solder Joint Metallurgy and Etching	31
5.5	Solderability of Termination Finishes	22	9.12	PWA Thermal Design	31
5.6	Soldering Considerations.....	22	9.13	Substrate Fabrication Information.....	32
5.7	CTE Mismatch Considerations.....	22	9.14	Component Derating, Applications, Qualification.....	32
5.8	ESD Packaging Requirements.....	23	9.15	Testability, Manufacturability	32
5.9	Specials or Custom Devices Use Precaution....	23	9.16	Vibration, Shock	32
5.10	Components to Avoid or to Use with Caution	23	9.17	Accelerated Life Testing.....	33
5.11	Component Selection Considerations for Military and Space Applications	23	9.18	Solder, Solderability, Soldered Assembly Quality.....	33
6.0	SOLDER MASK AND CONFORMAL COATING CONSIDERATION	23	9.19	Solder Mask and Conformal Coating	33
6.1	Solder Mask Considerations for SM.....	23	9.20	General Reliability	33
6.1.1	Solder Mask Selection.....	24	Appendix A Design for Reliability (DfR) of Solder Attachments		
6.1.2	Solder Mask Thickness Issues.....	24	A-1.0 SURFACE MOUNT SOLDER ATTACHMENT RELIABILITY		34
6.2	Temporary Solder Mask and Tapes.....	24	A-2.0 DAMAGE MECHANISMS AND FAILURE		34
6.3	Conformal Coatings.....	24	A-2.1	Solder Joints and Attachment Types	34
7.0	ASSEMBLY PROCESSES AND DESIGN FOR MANUFACTURABILITY	24	A-2.2	Global Expansion Mismatch	36
7.1	Solder Paste Application.....	26	A-2.3	Local Expansion Mismatch	36
7.2	Adhesive Application.....	26	A-2.4	Internal Expansion Mismatch.....	36
7.3	Component Placement	26	A-2.5	Solder Attachment Failure	36
7.4	Soldering	27	A-3.0 RELIABILITY PREDICTION MODELING		36
7.4.1	Solder Paste Reflow.....	27	A-3.1	Creep-Fatigue Modeling	36
7.4.2	Wave Soldering.....	27	A-3.2	Damage Modeling.....	37
7.5	Cleaning	27	A-3.3	CAVEAT 1 — Solder Joint Quality.....	38
7.6	Rework/Repair	27	A-3.4	CAVEAT 2 — Large Temperature Excursions	38
7.7	Depaneling	28	A-3.5	CAVEAT 3 — High-Frequency/ Low-Temperatures	39
7.8	Design for Manufacturability	28	A-3.6	CAVEAT 4 — Local Expansion Mismatch.....	39
7.8.1	Components.....	28	A.3.7	CAVEAT 5 — Very Stiff Leads/Very Large Expansion Mismatches	40
8.0	TESTING	28			
8.1	Design for Testability (DfT).....	29			

A-3.8 Statistical Failure Distribution and Failure Probability 40

A-3.9 Multiple Cyclic Load Histories 41

A-3.10 System Reliability Evaluation 41

A-4.0 DfR-PROCESS 42

A-5.0 CRITICAL FACTORS FOR EMERGING ADVANCED TECHNOLOGIES 42

A-5.1 Flip Chip on Laminate 42

A-5.2 Area Arrays (BGA, CGA)..... 43

A-5.3 Thin Packages (TSOP) 43

A-6.0 VALIDATION AND QUALIFICATION TESTS.... 44

A-7.0 SCREENING PROCEDURES 44

A-7.1 Solder Joint Defects..... 44

A-7.2 Screening Recommendations..... 45

A-8.0 STEP-BY-STEP NUMERICAL EXAMPLE RELATING REQUIRED DESIGN LIFE TO ACCELERATED RELIABILITY TEST RESULTS 45

A-9.0 REFERENCES..... 47

Appendix B Design for Reliability (DfR) of Plated-Through Via (PTV) Structures

B-1.0 PLATED-THROUGH VIA (PTV) RELIABILITY ISSUES 50

B-1.1 Copper Plating Process..... 50

B-1.1.1 Acid Copper Plating 50

B-1.1.2 Pyrophosphate Copper Plating 51

B-1.2 Material Properties..... 51

B-1.2.1 Tensile Properties..... 51

B-1.2.2 Ductility..... 51

B-1.2.3 Fatigue Behavior..... 51

B-1.3 Damage Mechanisms and Failure 52

B-1.3.1 PTV Quality 52

B-1.3.2 Impact of Assembly Processes and ESS Procedures 53

B-1.3.3 Impact of Test Procedures and Cyclic Operating Environments 54

B-2.0 RELIABILITY PREDICTION MODELING 54

B-3.0 DfR-PROCESS 56

B-4.0 CRITICAL FACTORS FOR EMERGING ADVANCED TECHNOLOGIES 57

B-5.0 VALIDATION AND QUALIFICATION TESTS.... 57

B-6.0 SCREENING PROCEDURES 57

B-7.0 REFERENCES..... 57

Appendix C Design for Reliability (DfR) of Insulation Resistance

C-1.0 INSULATION RESISTANCE DAMAGE MECHANISMS AND FAILURE 59

C-1.1 Surface Insulation Resistance (SIR)..... 59

C-1.2 Electrochemical Corrosion 59

C-1.3 Dendrite Growth 60

C-1.4 Conductive Anodic Filaments (CAF)..... 60

C-2.0 INSULATION RESISTANCE MODELING..... 60

C-2.1 Insulation Resistance Degradation 60

C-2.2 Conductive Anodic Filament Failure 61

C-3.0 DfR-PROCESS 61

C-4.0 CRITICAL FACTORS FOR EMERGING ADVANCED TECHNOLOGIES 62

C-5.0 VALIDATION AND QUALIFICATION TESTS.... 62

C-5.1 SIR Test Procedures..... 62

C-5.1.1 Factors Affecting SIR Readings Geometry..... 62

C-6.0 SCREENING PROCEDURES 63

C-7.0 REFERENCES 63

Appendix D Thermal Considerations

D-1.0 GENERAL..... 65

D-2.0 THERMAL ANALYSIS AT THE DEVICE LEVEL 65

D-2.1 The Ambient Temperature of an Electronic System (T_a) 65

D-2.2 The Temperature Rise of the Cooling Agent at the Device Level (ΔT_{CA})..... 66

D-2.3 The Temperature Rise Inside the Device Boundary Layer (ΔT_{BL})..... 66

D-2.4 The Temperature Rise Inside the Device Package (ΔT_p)..... 66

D-2.5 Thermal Wake (ΔT_{TW}) 66

D-3.0 DETERMINING THE SOLDER JOINTS TEMPERATURE SWINGS..... 66

D-4.0 COOLING OF ELECTRONIC EQUIPMENT 67

D-4.1 Radiation 67

D-4.2 Free Convection 67

D-4.3 Direct Forced Convection..... 67

D-4.4 Conduction Cooling 67

D-4.5 Heat Pipes 67

D-4.6 Direct Liquid Cooling..... 68

D-4.6.1 Direct Natural Convection Liquid Cooling 68

D-4.6.2 Direct Forced Liquid Cooling 68

D-5.0 PRODUCT THERMAL DESIGN..... 69

D-5.1	Component Level Cooling	69	E-11.0	ESD/EOS (Electrostatic Discharge/ Electrical Overstress)	78
D-5.2	Hot Parts	69	E-12.0	MOISTURE AND HUMIDITY	79
Appendix E Environmental Stresses			E-13.0	CORROSIVE GAS AMBIENT	79
E-1.0	THERMAL	72	E-14.0	TEMPERATURE/HUMIDITY/BIAS	80
E-1.1	Effects of Rework and Repair.....	72	E-15.0	SAND AND DUST	80
E-1.2	Glass Transition Temperature for Printed Boards	72	E-16.0	MECHANICAL SHOCK	80
E-1.3	Intermetallic Compound Growth.....	72	E-17.0	MECHANICAL VIBRATION	80
E-1.4	Glass Transition Temperature for Plastic Encapsulating	72	E-18.0	MECHANICAL OVERLOAD	81
E-1.5	Water Vapor Pressure Effects on Plastic Encapsulated Components.....	73	E-19.0	EM SUSCEPTIBILITY, RADIATION, INTERFERENCE	81
E-1.6	Water Vapor Pressure Effects on Printed Boards	73	E-20.0	LOW ATMOSPHERIC PRESSURE/HIGH ALTITUDE/VACUUM	81
E-1.7	Solder Melt Temperature Effects.....	73	E-21.0	IONIZING RADIATION	81
E-1.8	Temperature Excursion (ΔT) and Temperature Rate of Change ($\Delta T/\Delta t$).....	73	E-22.0	SOLVENTS	82
E-2.0	CHEMICAL	74	Appendix F Components		
E-2.1	PWA Cleanliness.....	74	F-1.0	CERAMIC LEADLESS CHIP CARRIER (CLLCC)	83
E-3.0	MECHANICAL	74	F-2.0	METAL ELECTRODE FACE BONDED (MELFs)	83
E-3.1	PWA Flexure	74	F-3.0	SPACING ABOVE BOARD	83
E-3.2	Tooling Impact.....	74	F-4.0	ALL SM PICK AND PLACE FEEDER PARTS..	83
E-4.0	ELECTRICAL	74	F-5.0	COMPONENTS WITH RUBBER SEALS	83
E-4.1	Electrostatic Discharge (ESD).....	74	F-6.0	PLASTIC SM COMPONENTS, MOISTURE, AND SM REFLOW PROCESSING	83
E-5.0	SMT FAILURES/STRESS CONDITIONS	74	F-6.1	Shorts and Resistive Shorts in PSMCs.....	84
E-5.1	Component Derating Reference Conditions	74	F-6.2	Opens and Intermittent Opens in PSMCs	84
E-5.2	The Most Important Stress and Some Precautions	74	F-6.3	PSMC Delamination and Thermal Resistance (θ_{jc} Degradation).....	85
E-5.3	Failure Modes/Failure Mechanisms	74	F-7.0	RESISTORS	85
E-6.0	OVERVIEW OF STRESSES	74	F-7.1	A Checklist for Power Resistors	85
E-6.1	Common Stresses and Component Response to Stress.....	74	F-7.2	Trimmed Resistors	86
E-7.0	IMPORTANCE OF TEMPERATURE AS A COMPONENT STRESS FACTOR	75	F-7.3	Fixed Resistors.....	86
E-7.1	Temperature-Related Reversible/Temporary Changes in Component Parameters	75	F-7.3.1	Metal Film Resistors.....	86
E-7.2	Temperature-Related Irreversible/Permanent Changes in Component Parameters	75	F-7.3.2	Thick-Film Resistor Networks	86
E-7.3	Effects of Low Temperature	76	F-7.3.3	Metal Oxide Film Resistors	86
E-7.4	Effects of Temperature Changes.....	76	F-7.3.4	Resistor chips	86
E-7.5	Thermal Shock.....	77	F-7.4	Variable Resistors	87
E-8.0	POWER	77	F-7.4.1	Enhancing Variable Resistor Reliability	87
E-9.0	VOLTAGE	77	F-8.0	CAPACITORS	88
E-10.0	CURRENT AND CURRENT DENSITY	78	F-8.1	Multilayer Ceramic Chip Capacitors	88
			F-8.2	Plastic Film Capacitors.....	88

F-8.3	Solid Tantalum Capacitors.....	89	APPENDIX I Solvents	
F-8.4	Electrolytic Aluminum Capacitors	89	I-1.0 INTRODUCTION.....	102
F-8.5	Variable Capacitors	89	I-2.0 MATERIALS AFFECTED	102
F-8.5.1	Variable Piston Capacitors.....	89	I-3.0 COMMON CLEANING SOLVENT FAMILIES ...	103
F-9.0	INDUCTOR/TRANSFORMERS	90	I-4.0 HCFC BLEND AND OTHER DATA.....	103
F-10.0	SEMICONDUCTORS	90	Appendix J Design for Testability	
F-10.1	Light Emitting Semiconductor Diode (LED) ...	90	J-1.0 DESIGN FOR TESTABILITY (DfT).....	105
F-10.2	Digital Semiconductors.....	91	J-1.1 Controllability	105
F-10.3	Digital Silicon Semiconductors (MOS MSI/LSI).....	91	J-1.2 Observability/Visibility	105
F-10.4	Linear Semiconductors	91	J-1.3 Partitioning.....	105
F-11.0	OTHER COMPONENTS	91	J-2.0 STANDARDS.....	105
F-11.1	Fuse	91	J-2.1 General	105
F-11.2	Separable Contacts (Relays, Switches, Connectors, Sockets)	91	J-2.2 Testability	105
F-11.2.1	Batteries.....	92	J-3.0 SUBSTRATE TESTING.....	105
F-11.2.2	Separable Electrical Interconnections	92	J-4.0 CHIP TESTING.....	106
F-12.0	PRINTED BOARD.....	93	J-5.0 PROBLEMS AND ISSUES OF UNPACKED ICs.....	106
F-12.1	Printed Board PTH/Vias	93	J-5.1 Availability.....	106
F-12.2	Printed Board Conductor Design	94	J-5.2 Confidence Level.....	106
F-12.3	Solder Joints.....	94	J-5.3 Vendor Concerns.....	106
			J-5.4 User Concerns.....	106
			J-5.5 Standards.....	106
Appendix G	Coefficient of Thermal Expansion		J-6.0 ASSEMBLY TESTING.....	106
G-1.0	COEFFICIENT OF THERMAL EXPANSION.....	96	J-7.0 APPROACHES TO SMT TESTING.....	106
G-2.0	CONSTRAINING CORES	96	J-7.1 Ad Hoc Techniques	107
			J-7.2 Structured Techniques.....	107
Appendix H	Electrostatic Discharge		J-7.2.1 Boundary-Scan	107
H-1.0	INTRODUCTION	99	J-7.2.2 BIST	107
H-1.1	ESD Susceptibility and Damage Prevention ...	99	J-7.2.3 Boundary-Scan Coupled with BIST.....	107
H-1.2	Current Limiting (ESD).....	99	J-7.3 Resistive Testing with Flying Probes.....	107
H-1.3	Susceptible Parts and Workarounds	99	J-7.4 Capacitance Testing	107
H-1.4	Assembly Process and Handling.....	99	J-7.5 Combined Resistance/Capacitance Testing	107
H-2.0	ESD DESIGN AND CHECKLIST	99	J-7.6 Glow Discharge	107
H-2.1	Hardware Design	99	J-7.7 Automatic Optical Inspection (AOI).....	107
H-2.2	Assembly Process and Handling.....	99	J-8.0 ISSUES AND CONCERNS OF TESTING.....	108
H-2.2.1	Firmware/Software ESD Design Guidelines	99	J-8.1 Test Equipment	108
H-2.2.2	Printed Board Design Guidelines	100	J-8.2 Test Points.....	108
H-2.2.3	Components.....	100	J-8.3 Costs.....	108
H-2.2.4	Cable	100	J-8.4 CAD/CAE Software	108
H-2.3	CLASS 1: Sensitivity Range 0 to 1,999 Volts	100	Appendix K Design for Manufacturability and Assembly Checklist	
H-2.4	CLASS 2: Sensitivity Range 2,000 to 3,999 Volts	101	K-1.0 SUMMARY	109
H-2.5	CLASS 3: Sensitivity Range 4,000 to 15,999 Volts	101		
H-2.6	CLASS "4": Sensitivity Range 16,000 Volts CONSIDERED NON-ESD SENSITIVE.....	101		

Appendix L Corrosion Basics and Checklist

L-1.0 CORROSION BASICS	111
L-2.0 CORROSION OF THE PWA	111
L-3.0 CORROSION IN COMPONENTS	111
L-4.0 OTHER EFFECTS OF WATER AND WATER VAPOR	111
L-5.0 FRETTING “CORROSION”	112
L-6.0 CORROSION DESIGN CHECKLIST	112
L-6.1 Galvanic Corrosion	114

Appendix M Solder Joint Variability

M-1.0 SOLDER JOINT VARIABILITY	116
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Appendix N Adhesives, Solder Mask and Conformal/Other Coatings

N-1.0 ADHESIVES	119
N-1.1 Electrically Conductive Attachment Materials.....	119
N-1.2 Thermally Conductive Adhesives.....	119
N-1.3 Mechanical Attachment Adhesives.....	119
N-2.0 SOLDER MASK	119
N-2.1 Types of Solder Masks	120
N-2.1.1 Liquid Screenprinted Solder Mask.....	120
N-2.1.2 Dry Film.....	120
N-2.1.3 Liquid Photoimageable	121
N-3.0 TEMPORARY MASKS AND STOPS	121
N-4.0 CONFORMAL COATING	121
N-4.1 Selection of Coating	122
N-4.2 Thermal Stress Design Considerations	122
N-4.3 Chemical Stress Design Considerations.....	122
N-4.4 Space Environment Design Considerations....	122
N-4.5 Manufacturing Considerations.....	122
N-4.6 Other Design Considerations.....	122

N-5.0 COMMON CRITICAL PROPERTIES OF SOLDER MASK AND CONFORMAL COATINGS	123
---	-----

N-6.0 JUNCTION COATINGS, “GLOB-TOPS”	124
---	-----

Appendix O Aerospace and High Altitude Concerns

O-1.0 INTRODUCTION	125
O-2.0 THERMAL DESIGN	125
O-3.0 LARGE THERMAL EXCURSIONS	125
O-4.0 CONTAMINATION	125
O-5.0 RADIATION ENVIRONMENT	126

O-6.0 ELECTRICAL PROPERTIES OF GASES	126
---	-----

O-7.0 GRAVITY (OR LACK OF)	126
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Appendix P Technical Acronyms and Abbreviations**Figures**

Figure 1–1 General Design Steps	3
Figure 1–2 Flow Chart for Reliability Assurance Processes ..	4
Figure 3–1 SMT Assembly Response to Thermal Shock	8
Figure 3–2 Thermal Relief in Ground Planes.....	12
Figure 3–3 Spacing Between Parts.....	13
Figure 6–1 Impact of Solder Mask Thickness on Stenciling	25
Figure 7–1 Type 1B Assembly – All SMT Components.....	25
Figure 7–2 Type 1C Assembly – Mixed Technology Assembly	25
Figure 7–3 Type 2B – All SMT Components.....	25
Figure 7–4 Type 2C – Mixed Technology.....	26
Figure A–1 Depiction of the Effects of the Accumulating Fatigue Damage in Solder Joint Structure	35
Figure A–2 Solder Joint Pull Strengths for Gullwing Leads Consisting of Alloy 42 from Different Vendors and Copper.....	39
Figure A–3 Effect of Component Offsets on the Fatigue Reliability of Three Capacitor Chip (CC) Sizes	44
Figure B–1 Cross-Section Schematic of a PTV With a Barrel Fracture Near the Center of the MLB	52
Figure B–1 Cross-Section Schematic of a PTV With a Barrel Fracture Near the Center of the MLB	52
Figure B–2 Schematic Cross-Sectional View of a PTV with a Shoulder Fracture in a printed board.....	53
Figure B–3 Reduction of Available Copper Ductility Due to Localized Nicks Reducing the Width of the FlexCircuit Conductors [Ref. B-7: 25] and PTV Stress Concentration Factor, K_c	56
Figure D–1 Thermal Vias and Planes.....	70
Figure D–2 Other Methods of Conductive Heat Transfer	70
Figure D–3 Use of Heat Slug.....	71

Tables

Table 1–1 The Design Team	1
Table 3–1 Realistic Representative ⁽¹⁾ Use Environments, Service Lives, and Acceptable Failure Probabilities for Surface Mounted Electronics Attachments by Use Categories	6
Table 4–1 Advantages and Disadvantages of Various Types of Substrates	18
Table 6–1 Solder Mask Guidelines	24
Table A–1 Realistic Representative ⁽¹⁾ Use Environments, Service Lives, and Acceptable Failure Probabilities for Surface Mounted Electronics Attachments by Use Categories	35

Table A-2	Quality of Solder Joints with Copper and Alloy 42 Resulting from Different Reflow Temperatures.....	38
Table B-1	Estimates of Tensile Properties of Copper Deposit Inside the PTVs	52
Table B-2	Estimates of the Fatigue Life and Time to Failure of PTVs in Some Typical Use Environments from Table A-1	57
Table C-1	SIR Test Parameters for Some Industry Tests...	63
Table G-1	Typical Values for Coefficients of Thermal Expansion (ppm/°C).....	96
Table G-2	Properties of Printed Circuit Laminates	98
Table K-1	Checklist for Design for Manufacturability and Assembly	109
Table L-1	Galvanic Compatibility of Metals	115

Design Guidelines for Reliable Surface Mount Technology Printed Board Assemblies

1.0 SCOPE

This document establishes design concepts, guidelines, and procedures intended to promote appropriate ‘Design for Reliability (DfR)’ procedures and to ensure reliable printed wiring assembly (PWA) characteristics. The major focus of the information presented is directed toward those PWAs that have surface mount (SM) components, either totally, or intermixed with through-hole components, mounted on one or both sides of the mounting structure.

1.1 Purpose The definition of reliability in this document is:

Reliability is the ability of a product to function under given conditions and for a specified period of time without exceeding acceptable failure levels.

This document addresses reliability-related aspects of product design, process design, as well as material/component selection and qualification. This document identifies appropriate existing IPC documents for basic detailed information.

The effort of this document is directed at SMT; the interconnect structure and the solder joint will receive most of our attention.

1.2 Design Philosophy Before the product design effort can begin, the designers of the product and assembly process need to know the customer’s reliability requirements for the product. These requirements should be defined and ranked by a concurrent engineering or cross-functional team through a process such as Quality Function Deployment (QFD), used to capture the voice of the customer.

1.2.1 Establishing the Design Team The design team can include but is not limited to the members who participate in at least the design activities identified in Table 1-1. In this table, DfA/M stands for Design for Assembly/Manufacturability, DfT for Design for Testability, DfR for Design for Reliability.

The design team can consider the general design guidelines and issues presented in the body of this document as a methodology for achieving its reliability goals. Figure 1-1 illustrates the general design steps and process flow using concurrent engineering. Figure 1-2 illustrates the interactive nature of the design for reliability process.

1.2.2 Defining Reliability Requirements The basic reliability requirements to be defined include:

Table 1-1 The Design Team

Design/Engineering Function	Team Improvement Area			
	(QFD)	(DfA/M)	(DfT)	(DfR)
Product	(QFD)	(DfA/M)	(DfT)	(DfR)
Circuit	(QFD)	(DfA/M)	(DfT)	
Printed board		(DfA/M)	(DfT)	(DfR)
Thermal	(QFD)			(DfR)
EMC, EMI, ESD	(QFD)		(DfT)	(DfR)
Mechanical	(QFD)	(DfA/M)	(DfT)	(DfR)
Software	(QFD)		(DfT)	
Marketing	(QFD)			
Process/manufacturing	(QFD)	(DfA/M)		
Test	(QFD)		(DfT)	(DfR)
Package/component		DfA/M	(DfT)	
Field Service	(QFD)		(DfT)	
Purchasing		(DfA/M)		
Material	(QFD)	(DfA/M)	(DfT)	(DfR)
Reliability	(QFD)	(DfA/M)	(DfT)	(DfR)
Regulations	(QFD)		(DfT)	
Upper management	(QFD)	Conceptual Design and Cultural Change		

- years of service
- acceptable failure rate(s)/probability(ies) as a function of time
- repair/replacement/upgrade/service/maintenance/warranty strategy
- life cycle environment(s)
- definition of acceptable performance
- criticality of function(s)
- available test equipment

1.2.3 Understanding the Product Life Cycle The life cycle begins at the component level (including the printed board) and continues through the assembly level; the life cycle includes exposure to the following environments:

- assembly/process
- testing
- storage
- transportation
- operating